Method for Permanent Bonding of Wafers

Abstract

This invention relates to a method for bonding of a first contact surface of a first substrate to a second contact surface of a second substrate with following steps, especially the following sequence:

- forming a reservoir in a surface layer on the first contact surface,
- at least partial filling of the reservoir with a first educt or a first group of educts,
- the first contact surface making contact with the second contact surface for formation of a prebond connection,
- forming a permanent bond between the first and second contact surface, at least partially strengthened by the reaction of the first educt with a second educt contained in a reaction layer of the second substrate.

Figure 5